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To the Honorable Assistant Secretary and C or copy(ies) thereof.

Please record the attached original document(s)

1. Name of conveying party(ies):
(1) Tetsuo SAJI; (2) Kumar Nabeen SHRESTHA
Additional name(s) of conveying party(ies) attached? No

2. Name and address of receiving party(ies):
Name: JAPAN SCIENCE AND TECHNOLOGY CORPORATION
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City: Saitami Country: JAPAN
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X Assignment Merger
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4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is:
A. Patent Application No.(s)
09/959,722, filed October 6, 2001
B. Patent No.(s)
Additional numbers attached? No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: WENDEROTH, LIND & PONACK, L.L.P.
Attn: Matthew Jacob, Esq.
Street Address: 2033 K Street, N.W., Suite 800
City: Washington, State: DC ZIP: 20006-1021

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41). \$40.00
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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Matthew Jacob, Reg. No. 25,154 *Matthew Jacob* December 4, 2001
Name of Person Signing Signature Date
Total number of pages including cover sheet: 3

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ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s)
of Inventor(s)

Tetsuo SAJI

Kumar Nabeen SHRESTHA

the undersigned hereby sell(s) and assign(s) to

Insert Name(s)
of Assignee(s)

JAPAN SCIENCE AND TECHNOLOGY CORPORATION

Address

of 1-8, Hon-cho 4-chome, Kawaguchi-shi, Saitami, JAPAN

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of
Invention

COMPOSITE PLATING METHOD

for which an application for patent in the United States has been executed by the undersigned

on November 22, 2001

Date of Signing
of Application

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, D.C. 20006-1021, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordal of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date November 22, 2001

Tetsuo Saji
Tetsuo SAJI

Date November 22, 2001

Kumar Nabeen SHRESTHA
Kumar Nabeen SHRESTHA

Date _____

Date _____

Date _____

Date _____

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness _____

Witness _____

ACKNOWLEDGMENT

_____ } ss

This _____ day of _____, 19____, before me personally came the

above-named _____ to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

Official Signature

Official Title

SEAL

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date October 6, 2001

Applicant Reference Number 01-F-004US/UA Atty Docket No. 2001-1655A

Title of Invention COMPOSITE PLATING METHOD